

Application S/N 10/806,844  
Amendment Dated: September 16, 2005  
Response to Office Action dated: May 19, 2005

CE12694JME

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (currently amended) A method of soldering a shield on a substrate, comprising the steps of:

applying solder onto conductive areas on the substrate including a conductive shield track for at least one shield;

placing components, if any, onto the conductive areas for the components;

reflowing the substrate thereby substantially simultaneously providing solder joints for the components and a selectively solder clad area over the conductive shield track;

applying flux to the to one among the at least one shield and the solder clad area;

placing the shield over the solder clad area; and

reflowing the substrate including the shield over the solder clad area.

2. (original) The method of claim 1, wherein the method further comprises the step of cleaning the substrate after reflowing the substrate when providing the solder clad area.

3. (original) The method of claim 1, wherein the step of applying flux further comprises the step of picking up the at least one shield and dipping the shield into the flux.

Application S/N 10/806,644  
Amendment Dated: September 16, 2005  
Response to Office Action dated: May 19, 2005

CE12694JME

4. (currently amended) The method of claim 1, wherein the step of applying solder paste onto the conductive shield track comprises the step of over printing the solder to increase the solder volume to the conductive shield track to accommodate for the shield's non-coplanarity.
5. (original) The method of claim 1, wherein the step of placing components comprises the step of placing surface mount components onto the substrate.
6. (original) The method of claim 1, wherein the step of applying solder comprises the step of applying solder paste onto the conductive areas forming conductive pads for the components and the shield track.
7. (original) The method of claim 1, wherein the step of applying solder comprises the step of applying solder preforms onto the conductive areas.
8. (original) The method of claim 1, wherein the step of applying solder comprises the step of screen printing solder paste onto the conductive areas.
9. (currently amended) A method of attaching a shield to a substrate, comprising the steps of:
  - circumscribing a predetermined area on the substrate with at least a portion of a metallized trace pattern;
  - applying solder to the metallized trace pattern;

Application S/N 10/806,644  
 Amendment Dated: September 16, 2005  
 Response to Office Action dated: May 19, 2005

CE12694JME

placing components on portions of the metallized trace pattern;  
 reflowing the solder to form substantially simultaneously a cladded trace pattern  
 on a portion of the metallized trace pattern reserved for the shield and solder joints for  
the components;  
 placing the shield on the cladded trace pattern; and  
 reflowing the substrate.

10. (original) The method of claim 9, wherein the step of applying solder comprises the  
 step of applying solder paste to the metallized trace pattern.

11. (original) The method of claim 9, wherein the step of applying the solder comprises  
 the step of applying solder preform to the metallized trace pattern.

12. (currently amended) The method of claim 9, wherein the step of placing  
 components ~~comprising~~ comprises the step of placing a semiconductor die on portions  
 of the metallized trace pattern.

13. (currently amended) A product having a substrate, comprising:  
 solder applied onto conductive areas on the substrate including a conductive  
 shield track for at least one shield;  
 components placed onto the conductive areas for the components, wherein the  
 solder paste applied to the conductive ~~runner~~ areas is reflowed providing a selectively  
 solder cladded area over the conductive shield track;

Application S/N 10/806,644  
Amendment Dated: September 16, 2005  
Response to Office Action dated: May 19, 2005

CE12694JME

a metallic shield place over the selectively solder clad area, wherein the substrate including the shield over the selectively solder clad area is reflowed.

14. (original) The product of claim 13, wherein the components placed onto the conductive areas for the components are surface mounted components.

15. (original) The product of claim 13, wherein the solder applied onto the conductive areas is solder paste.

16. (currently amended) The product of claim 13, wherein the solder applied onto the conductive areas is solder preforms.

17. (original) A processed printed circuit board, comprising:

a predetermined area on a substrate defined by a metallized trace pattern;

solder applied to the metallized trace pattern;

components placed on portions of the metallized trace pattern, wherein the processed printed circuit board is reflowed a first time; and

a shield placed over a clad portion of the metallized trace pattern, wherein the processed printed circuit board is reflowed a second time.